

S/N 09/253,611

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Serial No.: 09/253,611

Filed: February 19, 1999

Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

Examiner: Ron Pompey

Group Art Unit: 2812

Docket: 303.572US1

PATENT

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on February 13, 2002. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 1, 3, 9-11, and 71. The specific amendments to individual claims are detailed in the following marked up set of claims.

1.(Amended) A method of forming a solder ball contact, comprising:

forming a metal contact pad on a substrate;

forming an insulating layer on the metal contact pad;

removing a portion of the insulating layer to expose a portion of the metal contact pad, thereby forming an exposed portion of the metal contact pad, the exposed portion having a predetermined diameter;

[immersing the substrate in molten solder;]

depositing solder on the exposed portion of the metal contact pad, wherein depositing solder on the exposed portion of the metal contact pad uses a deposition selected from a group consisting of [using] selective chemical vapor deposition [or] and selective electrolytic deposition, thereby forming a solder contact by selectively depositing solder only on the exposed portion of the metal contact without depositing solder on the insulating layer and without removing a remaining portion of the insulating layer; and